INTEGRATED CIRCUITS

DATA SHEET

74F1244 Octal buffer (3-State)

Product specification

1989 Apr 04

IC15 Data Handbook





Octal buffer (3-State)

74F1244

FEATURES

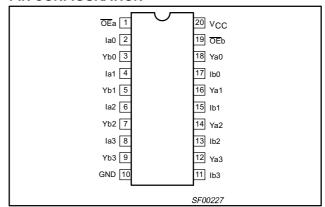
- High impedance NPN base inputs for reduced loading (20μA in High and Low states)
- Low power, light loading
- Functional pin-for-pin equivalent of 74F244
- 1/30th the bus loading of 74F244
- Provides ideal interface and increase fan-out of MOS microprocessors
- Octal bus interface
- 3-State buffer outputs sink 64mA and source 15mA

DESCRIPTION

The 74F1244 is an octal buffer that is ideal for driving bus lines or buffer memory address registers. The outputs are capable of sinking 64mA and sourcing up to 15mA, producing very good capacitive drive characteristics. The device features two Output Enables, $\overline{\text{OE}}$ a and $\overline{\text{OE}}$ b, each controlling four of the 3-State outputs.

The 74F1244 is pin and functionally compatible with the 74F244. The lower power and light bus loading features make it an ideal part to interface directly with MOS microprocessors.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F1244	4.5ns	43mA

ORDERING INFORMATION

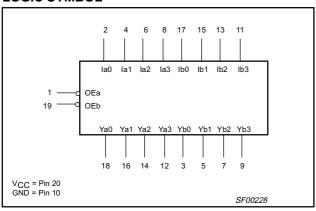
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C	DRAWING NUMBER
20-pin plastic DIP	N74F1244N	SOT146-1
20-pin plastic SOL	N74F1244D	SOT163-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

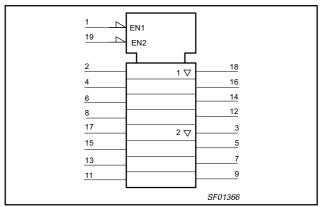
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
lan, Ibn	Data inputs	1.0/0.033	20μΑ/20μΑ
ŌĒa, ŌĒb	Output enable inputs (active Low)	1.0/0.033	20μΑ/20μΑ
Yan, Ybn	Data outputs	750/106.7	15mA/64mA

NOTE: One (1.0) FAST unit load is defined as: $20\mu A$ in the high state and 0.6mA in the low state.

LOGIC SYMBOL



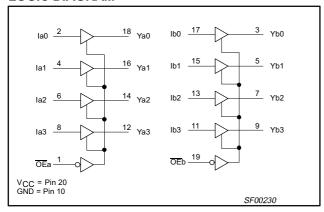
IEC/IEEE SYMBOL



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LOGIC DIAGRAM



FUNCTION TABLE

	INP	JTS		OUTPUTS			
OE a	la	OE b	lb	Ya	Yb		
L	L	L	L	L	L		
L	Н	L	Н	Н	Н		
Н	Х	Н	Х	Z	Z		

High voltage level Low voltage level

L = Low voltage level
X = Don't care
Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state	128	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		LIMITS		UNIT
STWIBUL	PARAMETER	MIN	NOM	MAX	UNII
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I _{IK}	Input clamp current			-18	mA
I _{OH}	High-level output current			-15	mA
I _{OL}	Low-level output current			64	mA
T _{amb}	Operating free-air temperature range	0		+70	°C

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	DADAMETER		TE	ST CONDITIONS	1		LIMITS		UNIT
SYMBOL	PARAMETER		16	SI CONDITIONS	o '	MIN	TYP ²	MAX	UNII
		±10% V _{CC}							V
	High-level output voltage		$V_{CC} = MIN,$ $V_{IL} = MAX,$	$I_{OH} = -3mA$	±5% V _{CC}	2.7	3.4		V
V _{OH}	High-level output voltage		V _{IH} = MIN	Jan. = 15mA	±10% V _{CC}	2.0			V
				I _{OH} = –15mA	±5% V _{CC}	2.0			V
V	Law lavel autout valtage		V _{CC} = MIN, V _{IL} = MAX,	I _{OL} = 48mA	±10% V _{CC}		0.38	0.55	V
V _{OL}	Low-level output voltage		V _{IH} = MIN	I _{OL} = 64mA	±5% V _{CC}		0.42	0.55	V
V _{IK}	Input clamp voltage		V _{CC} = MIN, I _I	= I _{IK}			-0.73	-1.2	V
I _I	Input current at maximum input	voltage	V _{CC} = 0.0V, V			100	μΑ		
I _{IH}	High-level input current		V _{CC} = MAX, \			20	μΑ		
I _{IL}	Low-level input current		V _{CC} = MAX, \	/ _I = 0.5V			-20	μΑ	
l _{ozh}	Off-state output current, High-level voltage applied		V _{CC} = MAX, \			50	μА		
I _{OZL}	Off-state output current, Low-level voltage applied		$V_{CC} = MAX, V_O = 0.5V$					-50	μА
Ios	Short-circuit output current ³		V _{CC} = MAX		-100		-225	mA	
	Іссн						30	40	mA
Icc	Supply current (total)		V _{CC} = MAX		57	75	mA		
		I _{CCZ}					43	58	mA

NOTES:

AC ELECTRICAL CHARACTERISTICS

				LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	$T_{amb} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50pF, R_{L} = 500\Omega$			T _{amb} = 0°C V _{CC} = +5. C _L = 50pF,	UNIT				
			MIN	TYP	MAX	MIN	MAX				
t _{PLH}	Propagation delay	Waveform 1	2.5	4.0	5.5	2.5	6.0	ns			
t _{PHL}	Ian, Ibn to Yn		2.0	5.0	7.0	2.0	7.5	ns			
t _{PZH}	Output Enable time to High or Low level	Waveform 2	3.0	6.0	7.5	3.0	8.5	ns			
t _{PZL}		Waveform 3	3.0	6.5	8.0	3.0	8.5	ns			
t _{PHZ}	Output Disable time	Waveform 2	2.0	4.0	5.5	2.0	6.0	ns			
t _{PLZ}	to High or Low level	Waveform 3	2.0	4.0	5.5	2.0	6.0	ns			

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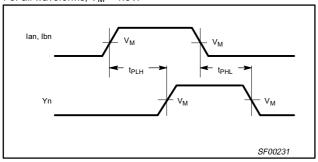
For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
 Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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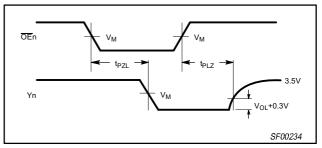
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AC WAVEFORMS

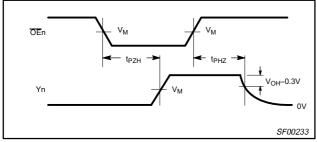
For all waveforms, $V_M = 1.5V$.



Waveform 1. For Non-Inverting Outputs

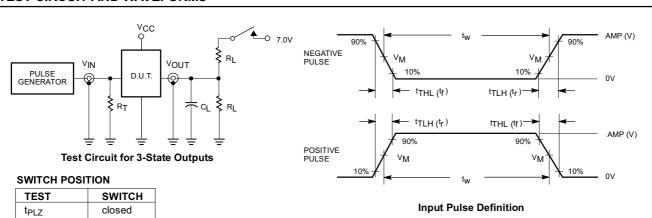


Waveform 3. 3-State Output enable Time to Low Level and Output Disable Time from Low Level



Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level

TEST CIRCUIT AND WAVEFORMS



t_{PZL} closed All other open

DEFINITIONS:

R_L = Load resistor; see AC electrical characteristics for value.

C_L = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

familia	INP	INPUT PULSE REQUIREMENTS											
family	amplitude	V _M	rep. rate	t _w	t _{TLH}	t _{THL}							
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns							

SF00777

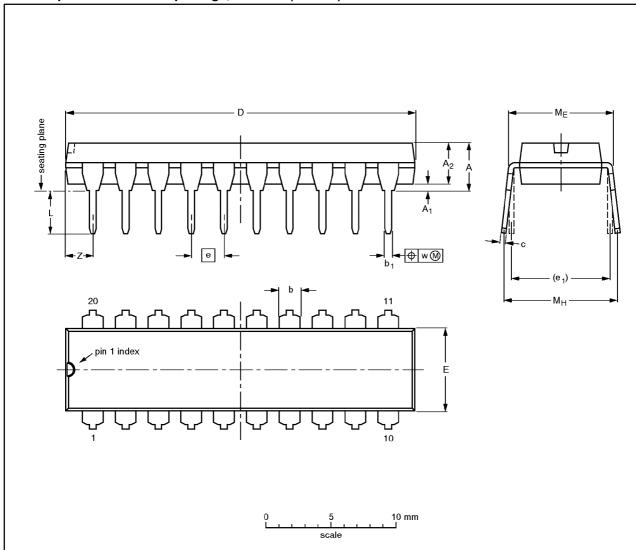
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DIP20: plastic dual in-line package; 20 leads (300 mil)





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	VEDSION			EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUEDATE
SOT146-1			SC603		92-11-17 95-05-24

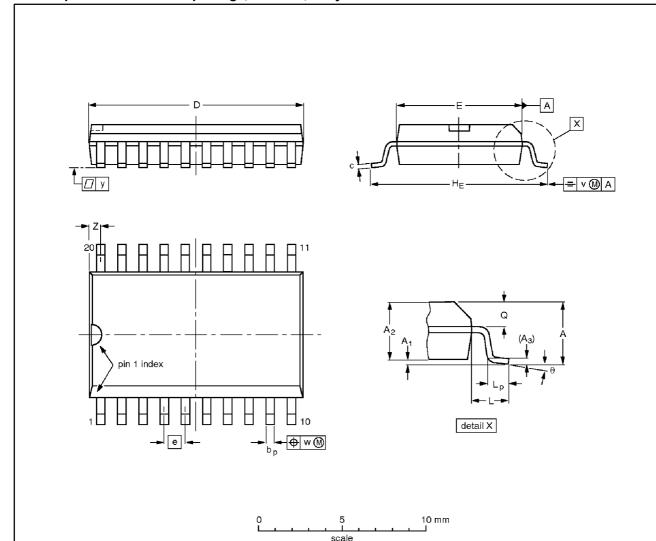
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SO20: plastic small outline package; 20 leads; body width 7.5 mm





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

	menorous (incli dimensions are derived from the original initial dimensions)																	
UNIT	A max.	A 1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	e	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055		0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN	ISSUE DATE	
	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC				-95-01-24 97-05-22

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Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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